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(21) Application number: **08183444**(71) Applicant: **TOSHIBA CHEM CORP**(22) Date of filing: **12.07.98**(72) Inventor: **FURUHASHI JUN****(54) ELECTRONIC TAG AND ITS MANUFACTURING METHOD**

the movement of the internal parts by the pressure of the resin at the time of molding the external ornamental part can be prevented to improve productivity.

**(57) Abstract**

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**PROBLEM TO BE SOLVED:** To easily obtain a sheathing resin which has high mechanical strength and excellent environmental resistance in an electronic tag in which internal parts such as IC chips and an antenna are necessary to be protected by the sheathing resin.

**SOLUTION:** An internal parts holding parts 33 having a recessed part 33a for housing the internal parts and a projection 35 for positioning in a metallic mold is prepared, the internal parts are housed in the recessed part 33a and, then, the resin is injected in the recessed part and is solidified to form a protective fixing layer 35 for protecting and fixing the internal parts and, further, an external ornamental part is molded by the metallic mold so as to envelop the internal parts holding parts. Since both the protective fixing layer and the external ornamental part protect the internal parts, the protective fixing layer prevent the internal parts from being in contact with moisture even in the case of moisture immersion to inside from minute cracks, etc., generated in the external ornamental part. Further, since the internal parts housed in the recessed part in the internal parts holding parts are fixed by the protective fixing layer,

